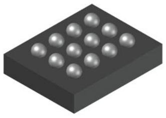


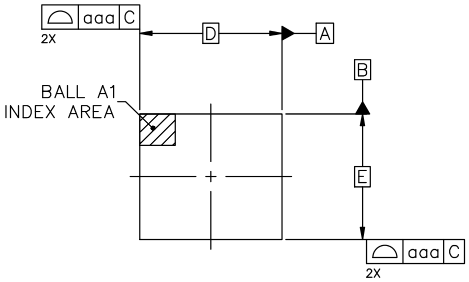
WLCSP12 1.76x1.56x0.32, 0.40P
CASE 568AP
ISSUE B

DATE 24 APR 2024

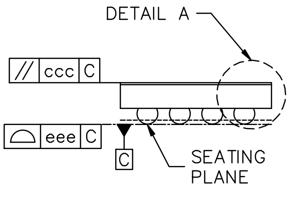
NOTES:

1. DIMENSIONING AND TOLERANCING CONFORM TO ASME Y14.5−2018.
2. ALL DIMENSIONS ARE IN MILLIMETERS.
3. DIMENSION b IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER PARALLEL TO DATUM C.
4. COPLANARITY APPLIES TO THE SPHERICAL CROWNS OF THE SOLDER BALLS.
5. DATUM C, THE SEATING PLANE IS DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.

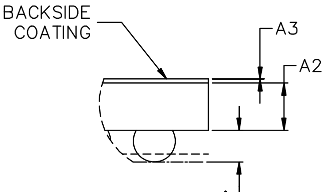
DIM	MILLIMETERS		
	MIN	NOM	MAX
A	0.480	0.515	0.550
A1	0.176	0.196	0.216
A2	0.282	0.294	0.306
A3	0.022	0.025	0.028
b	0.250	0.265	0.280
D	1.760 BSC		
D1	0.265	0.280	0.295
E	1.560 BSC		
E1	0.365	0.380	0.395
e	0.400 BSC		
TOLERANCES OF FORM AND POSITION			
aaa	0.030		
bbb	0.050		
ccc	0.100		
ddd	0.030		
eee	0.050		



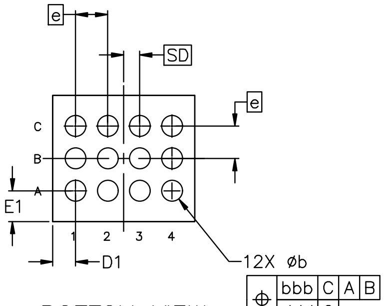
TOP VIEW



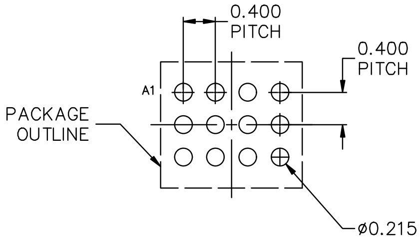
SIDE VIEW



DETAIL A'
SCALE 2:1



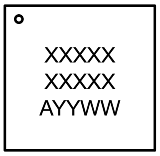
BOTTOM VIEW



RECOMMENDED MOUNTING FOOTPRINT*

*FOR ADDITIONAL INFORMATION ON OUR Pb−FREE STRATEGY AND SOLDERING DETAILS, PLEASE DOWNLOAD THE ONSEMI SOLDERING AND MOUNTING TECHNIQUES REFERENCE MANUAL, SOLDERRM/D.

GENERIC MARKING DIAGRAM*



XXXX = Specific Device Code
A = Assembly Location
YY = Year
WW = Work Week

*This information is generic. Please refer to device data sheet for actual part marking. Pb−Free indicator, “G” or microdot “▪”, may or may not be present. Some products may not follow the Generic Marking.

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DESCRIPTION:	**WLCSP12 1.76x1.56x0.32, 0.40P**	**PAGE 1 OF 1**

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